



Material Content Data Sheet



Halogen-Free

Sales Product Name	IAUC100N08S5N031	Issued	11. April 2021
MA#	MA005346533		
Package	PG-TDSON-8-34	Weight*	113.62 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.207	1.94	1.94	19423	19423
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		140	
	non noble metal	iron	7439-89-6	0.053	0.05		466	
	non noble metal	copper	7440-50-8	52.842	46.53	46.59	465058	465664
wire	noble metal	gold	7440-57-5	0.042	0.04	0.04	370	370
encapsulation	organic material	carbon black	1333-86-4	0.073	0.06		643	
	plastics	epoxy resin	-	5.773	5.08		50809	
	inorganic material	silicondioxide	60676-86-0	30.693	27.01	32.15	270123	321575
leadfinish	non noble metal	tin	7440-31-5	1.574	1.39	1.39	13851	13851
plating	noble metal	silver	7440-22-4	0.209	0.18	0.18	1841	1841
solder	non noble metal	tin	7440-31-5	0.047	0.04		413	
	noble metal	silver	7440-22-4	0.059	0.05		516	
	non noble metal	lead	7439-92-1	2.239	1.97	2.06	19705	20634
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005			44	
	non noble metal	iron	7439-89-6	0.017	0.01		148	
	non noble metal	copper	7440-50-8	16.828	14.81	14.82	148098	148290
clip plating	noble metal	silver	7440-22-4	0.639	0.56	0.56	5624	5624
heatspreader	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	iron	7439-89-6	0.000			3	
	non noble metal	copper	7440-50-8	0.310	0.27	0.27	2724	2728
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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